

OPEN Author Correction: Active Printed **Materials for Complex Self-Evolving Deformations**

Dan Raviv¹, Wei Zhao⁶, Carrie McKnelly³, Athina Papadopoulou³, Achuta Kadambi¹, Boxin Shi^{1,5}, Shai Hirsch⁴, Daniel Dikovsky⁴, Michael Zyracki², Carlos Olquin², Ramesh Raskar¹ & Skylar Tibbits3

Correction to: Scientific Reports https://doi.org/10.1038/srep07422, published online 18 December 2014

A supplementary file containing Appendices A and B was omitted from this Article and is provided below.

Additional Information

Supplementary information accompanies this paper at https://doi.org/10.1038/s41598-018-32403-4.

Open Access This article is licensed under a Creative Commons Attribution 4.0 International License, which permits use, sharing, adaptation, distribution and reproduction in any medium or format, as long as you give appropriate credit to the original author(s) and the source, provide a link to the Creative Commons license, and indicate if changes were made. The images or other third party material in this article are included in the article's Creative Commons license, unless indicated otherwise in a credit line to the material. If material is not included in the article's Creative Commons license and your intended use is not permitted by statutory regulation or exceeds the permitted use, you will need to obtain permission directly from the copyright holder. To view a copy of this license, visit http://creativecommons.org/licenses/by/4.0/.

© The Author(s) 2018

¹Camera Culture Group, Media Lab, Massachusetts Institute of Technology, 75 Amherst St, Cambridge, MA, USA. ²Bio/Nano/Programmable Matter Group, Autodesk Research, Autodesk Inc. Pier 9, San Francisco, CA, USA. ³Self-Assembly Laboratory, Massachusetts Institute of Technology, 265 Massachusetts Ave, Cambridge, MA, USA. ⁴Stratasys, ltd. Rehovot Science Park, Rehovot, Israel. ⁵Singapore University of Technology and Design, 20 Dover Dr, Singapore, Singapore. ⁶Bio/Nano/Programmable Matter Group, Autodesk Research, Autodesk Software Co., Ltd. 399 Pu Dian Road, Shanghai, Pudong District, Shanghai, P. R. China. Correspondence and requests for materials should be addressed to D.R. (email: darav@mit.edu)

Published online: 22 October 2018